



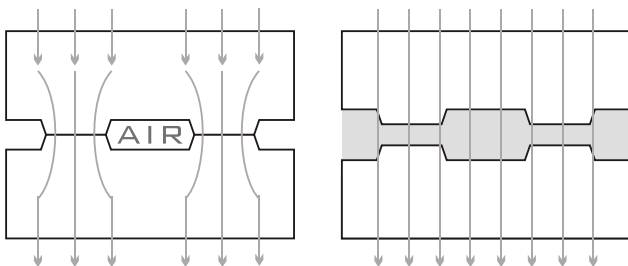
High Performance Thermal Compound Kit

PRODUCT RELEASE

Cooler Master HTK-002 thermally conductive compounds are grease-like silicone materials, heavily filled with heat conductive metal oxides. This combination promotes high thermal conductivity, low bleed and high-temperature stability. These compounds resist changes in consistency at temperatures up to 177 °C (350 °F), maintaining a positive heat sink seal to improve heat transfer from the electronic device to the heat sink or chassis, thereby, increasing the overall efficiency of the device.

FEATURES

- ▶ Suitable for CPU, chipsets on Mainboard, VGA card, etc.
- ▶ Easy to use
- ▶ Zif Socket Templates ensure correct applying area with various CPU socket types.
- ▶ Produces an even layer when using applicator.
- ▶ Dielectric.
- ▶ Wide range of application temperature



Since air is known as a poor heat conductor, it should be replaced by a more conductive material to improve heat flow across thermal interfaces.



Cautions

- ▶ For industrial use only.
- ▶ Keep out of the reach of children.
- ▶ Do not swallow!
- ▶ Avoid contact with eyes.
- ▶ Please read the instructions prior to installation.

SPECIFICATION / HTK-002

| | |
|--|---------------------------|
| Color | Gray |
| Viscosity (@25 °C) | 1400 P |
| Specific Gravity @ 25 °C | 2.63 g/cm ³ |
| Bulk Thermal Conductivity | >4.5 W/m-K |
| Thermal Impedance | ~0.02 C-in/W |
| Volume Resistivity | 5.0 x 10 ¹⁵ cm |
| Dielectric Properties (Dielectric constant @ 25 °C, 100Hz) | Insulating >6 |
| Shelf Life | 24 months from DOM |
| Evaporation (200 °C x 24hr) | <0.35% |

For product information please visit our website.
<http://www.coolermaster.com>